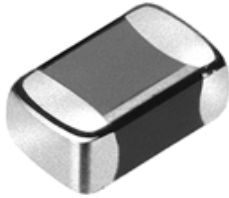




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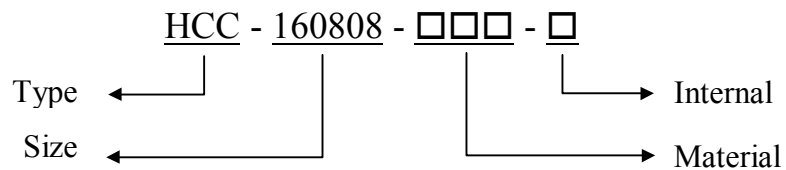
High Current Chip Beads, HCC Series

Feature:

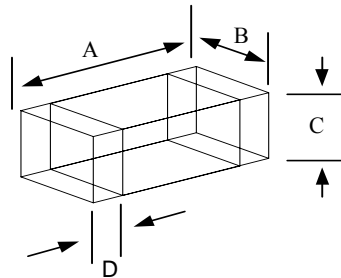


Our SMD High Current Chips Beads is specially designed to with Stand large Currents while providing a means of EMI/RFI attenuation for electronics products. Its has a full range different sizes to choose from.

Ordering Code:



Dimension in mm:



Type	A	B	C	D
HCC - 160808	1.6 ± 0.2	0.8 ± 0.15	0.8 ± 0.15	0.4 ± 0.2
HCC - 201209	2.0 ± 0.2	1.25 ± 0.2	0.9 ± 0.2	0.5 ± 0.3
HCC - 321611	3.2 ± 0.2	1.6 ± 0.2	0.6 ± 0.2	0.5 ± 0.3
HCC - 451616	4.5 ± 0.25	1.6 ± 0.2	1.6 ± 0.2	0.5 ± 0.3
HCC - 453215	4.5 ± 0.25	3.2 ± 0.2	1.5 ± 0.2	0.5 ± 0.3

Electrical:

Part Number	Impedance	Current
HCC-160808 - Series	11 Ω to 25 Ω	5000 mA to 4000 mA
HCC-201209 - Series	11 Ω to 80 Ω	5000 mA to 4000 mA
HCC-321611 - Series	26 Ω to 90 Ω	6000 mA to 5000 mA
HCC-451616 - Series	60 Ω to 80 Ω	6000 Ma to 5000 mA
HCC-453215 - Series	70 Ω to 120 Ω	6000 mA to 4000 mA

- ⇒ [General Component Specification](#)
- ⇒ [Tape and Reel](#)

[Next](#)

[Back](#)



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High Current Chip Beads, HCC Series

Electrical:

Part Number	Impedance (ohm)	Test Frequency (MHz)	DC Resistance (ohms) Max	Rated Current (mA) Max
HCC – 160808 - 110	11 ± 25%	100	0.015 Ω	5000
HCC – 160808 - 250	25 ± 25%	100	0.015 Ω	4000
HCC – 201209 - 110	11 ± 25%	100	0.010Ω	6000
HCC – 201209 - 320	32 ± 25%	100	0.025Ω	4000
HCC – 201209 - 600	60 ± 25%	100	0.025Ω	4000
HCC – 201209 - 800	80 ± 25%	100	0.030Ω	4000
HCC – 321611 - 260	26 ± 25%	100	0.015Ω	6000
HCC – 321611 - 320	32 ± 25%	100	0.015Ω	6000
HCC – 321611 - 500	50 ± 25%	100	0.020Ω	5000
HCC – 321611 - 700	70 ± 25%	100	0.020Ω	5000
HCC – 321611 – 800	80 ± 25%	100	0.025Ω	5000
HCC – 321611 - 900	90 ± 25%	100	0.030Ω	5000
HCC – 451616 – 600	60 ± 25%	100	0.020Ω	6000
HCC – 451616 – 700	70 ± 25%	100	0.025Ω	6000
HCC – 451616 – 800	80 ± 25%	100	0.025Ω	5000
HCC – 453215 – 700	70 ± 25%	100	0.030Ω	6000
HCC – 453215 – 121	120 ± 25%	100	0.030Ω	4000

[Next](#)

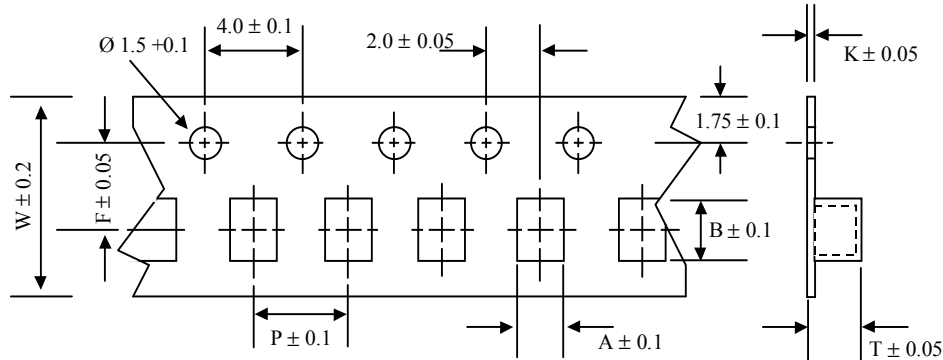
[Back](#)



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High Current Chip Beads, HCC Series

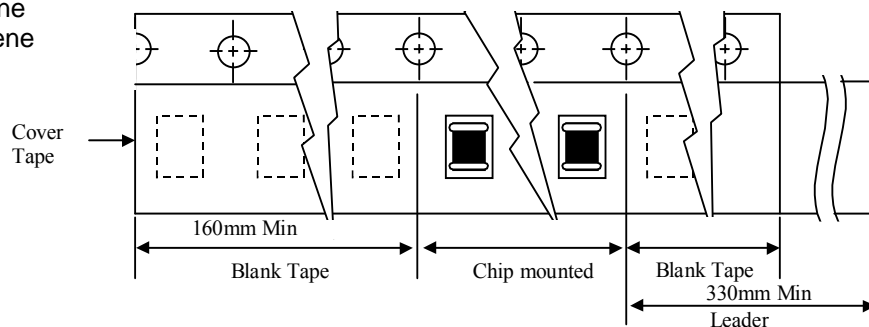
Tape Dimensions:



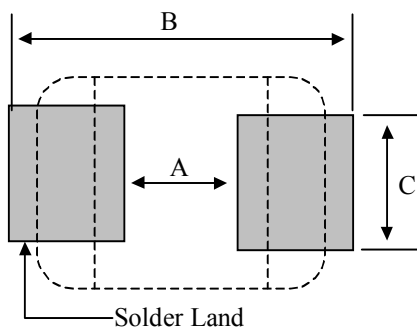
Type	A	B	T	W	P	F	K
HCC-160808	1.14	1.75	1.15	8.0	4.0	3.5	0.2
HCC-201209	1.54	2.32	1.15	8.0	4.0	3.5	0.2
HCC-321611	1.94	2.54	1.29	8.0	4.0	3.5	0.2
HCC-451616	1.94	4.94	1.90	12.0	4.0	5.5	0.3
HCC-453215	3.64	4.94	1.80	12.0	8.0	5.5	0.3

Tape Material:

Carrier Tape: Polystyrene
Cover Type : Polyethylene



Recommended Pattern:



Type	A	B	C
HCC-160808	0.8	2.4 ~ 3.4	0.6
HCC-201209	1.2	3.0 ~ 4.0	1.0
HCC-321611	2.0	4.2 ~ 5.2	1.2
HCC-451616	3.0	5.5 ~ 6.5	1.2
HCC-453215	3.0	5.5 ~ 6.5	2.4

[Next](#)

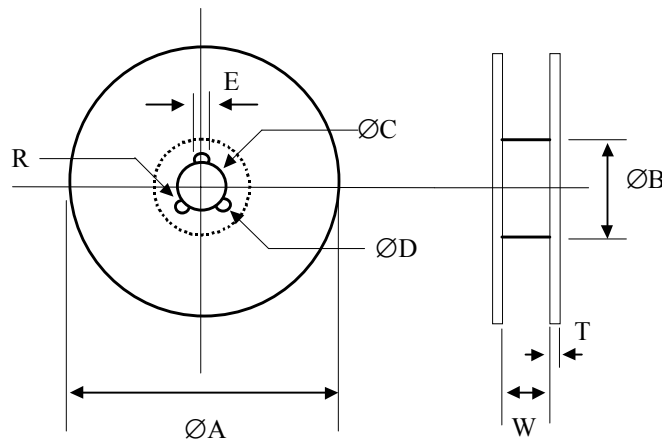
[Back](#)



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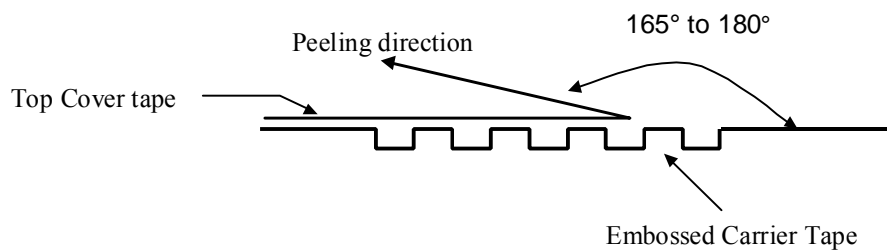
High Current Chip Beads, HCC Series

Reel Dimensions:



$\varnothing A$	$\varnothing B$	$\varnothing C$	$\varnothing D$	E	W	T	R
178 ± 2	60 ± 1	13.0 ± 0.5	21.0 ± 0.8	2.0 ± 0.5	10.0 ± 1.0	2.0 ± 0.5	1.0

Tape peeling:



[Next](#)

[Back](#)

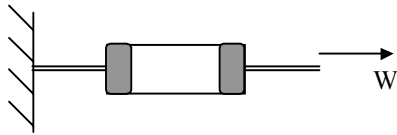
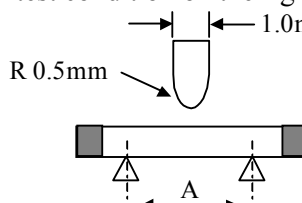


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High Current Chip Beads, HCC Series

General Component Specification for Chips Beads

Reliability Test (Mechanical Performance Test)

No.	Item	Specification	Test Condition		
1.	Solderability	More than 90% of the terminal electrode shall be covered with fresh solder	Pre heat: 100°C to 150°C Pre heat Time: 1 minute Solder: H63A (Eutectic Solder) Solder Temperature: 230 ± 5°C Flux: Rosin Dip Time: 3 ± 1 seconds		
2.	Soldering Heat Resistance	The chips shall not crack. More than 75% of the Terminal Electrode shall be covered with solder	Pre heat: 100°C to 150°C Pre heat Time: 1 minute Solder: H63A (Eutectic Solder) Solder Temperature: 260 ± 5°C Flux: Rosin Dip Time: 10 ± 1 seconds		
3.	Terminal Strength	The terminal electrode shall not break off nor the ferrite damage 	Type	Kgf (min)	Time
			1608	0.6 kg	30 sec ± 5 Sec
			2012	0.6 kg	
			3216	1.0 kg	
			others	1.5 kg	
4.	Bending strength	The ferrite shall not be damaged by force applied per test condition on the right 	Type	A (mm)	Kgf
			1608	1.0	0.6
			2012	1.4	1.0
			321611	2.0	2.0
			451616	2.5	2.5
			453215	2.7	2.5

Reliability Test (Climatic Test)

No	Item	Specification	Test Condition
5.	Thermal Shock (Temperature cycle)		Temperature: -55°C +125°C for 30 minutes, 50 Cycles
6.	Humidity Resistance	Impedance value shall be within ±20% of the initial value.	Temperature: +60°C ± 2°C Humidity: 90% to 95% Time 1000 ± 12 Hours
7.	High Temperature Resistance	DCR shall be within ±20% of initial value	Temperature: +80°C ± 2°C Humidity: 20% Time 1000 ± 12 Hours

[Next](#)

[Back](#)